Special Issue

Software Product Line in the Real World

Message from the Guest Editors

We cordially invite you to submit your papers for the Special Issue “Software Product Line in the Real World” in Applied Sciences. Software product line engineering (SPLE) has been adopted across the industry. Organizations in the domains that engineer software-intensive products have benefited from applying SPLE.

We seek contributions from the practitioners and researchers in industry and academia on the practices and theories applied to engineering SPLs in the real world in this new context.

The topics of this Special Issue include, but are not limited to, the following in industrial applications of SPLE across all lifecycle stages of SPLE:
Organizational and business aspects; Adopting or migrating to product-line engineering; Scoping of product portfolios; Architecture, design, and implementation of product lines; Quality and non-functional properties; Product line testing, verification, and validation; Process aspects; Variability management across all lifecycle stages; Comparison and assessment of tools in the industry; Version and configuration management; Theory, methods, or techniques used in the industry. SI Link: **special_issues/Software_Product**

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Deadline for manuscript submissions

closed (15 December 2021)

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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